

**Description**

The SX40P03DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = -30V$   $I_D = -40A$

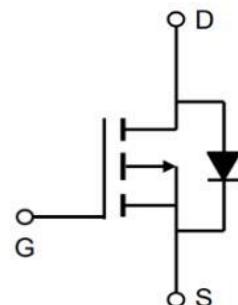
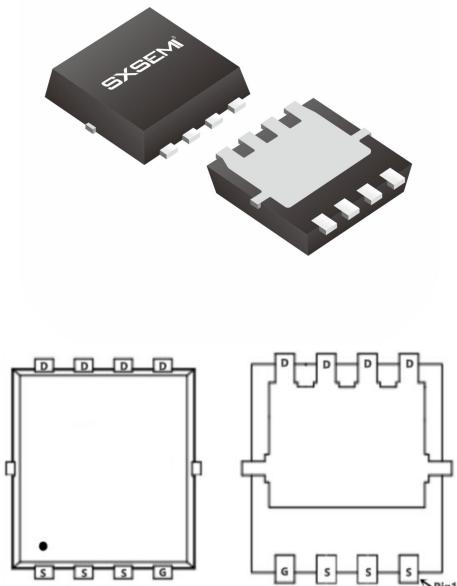
$R_{DS(ON)} < 16m\Omega$  @  $V_{GS} = -10V$

**Application**

Lithium battery protection

Wireless impact

Mobile phone fast charging

**PDFN3\*3-8L****Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-40	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-23	A
$IDM$	Pulsed Drain Current <sup>2</sup>	-120	A
$EAS$	Single Pulse Avalanche Energy <sup>3</sup>	68	mJ
$IAS$	Avalanche Current	-29.4	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	3.1	W
$P_D @ T_A = 70^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	75	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10s$ )	40	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	24	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$V(BR)DSS$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-30	-32.5	-	V
$IDSS$	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}$ , $V_{GS} = 0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$IGSS$	Gate to Body Leakage Current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	-1.2	-1.5	-2.5	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note3	$V_{GS} = -10\text{V}$ , $I_D = -10\text{A}$	-	10.5	16	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$ , $I_D = -5\text{A}$	-	16	20	
$R_g$	Gate Resistance	$V_{DS} = 0\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$	4.9	7.0	9.1	$\Omega$
$C_{iss}$	Input Capacitance	$V_{DS} = -24\text{V}$ , $V_{GS} = 10\text{V}$ , $f = 1.0\text{MHz}$	-	2130	-	pF
$C_{oss}$	Output Capacitance		-	280	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	252	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -24\text{V}$ , $I_D = -1\text{A}$ , $V_{GS} = -10\text{V}$	-	22	-	nC
$Q_{gs}$	Gate-Source Charge		-	4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5.8	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -24\text{V}$ , $I_D = -1\text{A}$ , $V_{GS} = -10\text{V}$ , $R_{GEN} = 7.0\Omega$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
$t_f$	Turn-off Fall Time		-	20	-	ns
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-29.5	A
$ISM$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-44	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_S = -1\text{A}$	-	-0.74	-1.2	V

**Note :**

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、 The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 4、 EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD} = -24\text{V}$ ,  $V_G = -10\text{V}$ ,  $R_G = 7\Omega$ ,  $L = 0.1\text{mH}$ ,  $I_{AS} = -29.5\text{A}$
- 5、 The data is theoretically the same as  $ID$  and  $IDM$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

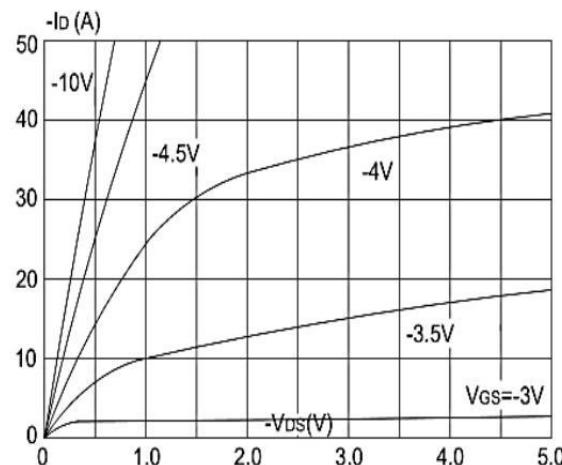


Figure 1: Output Characteristics Figure  
 $R_{DS(ON)}$  ( $\text{m}\Omega$ )

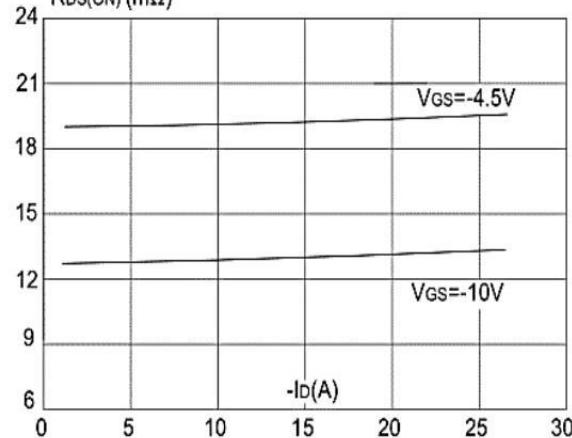


Figure 3: On-resistance vs. Drain Current  
 $-V_{GS}$  (V)

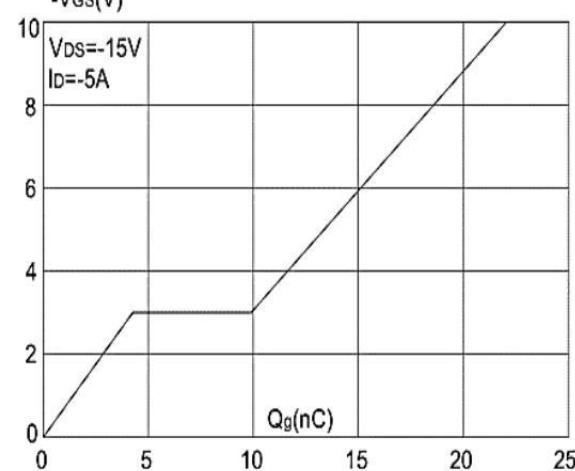


Figure 5: Gate Charge Characteristics

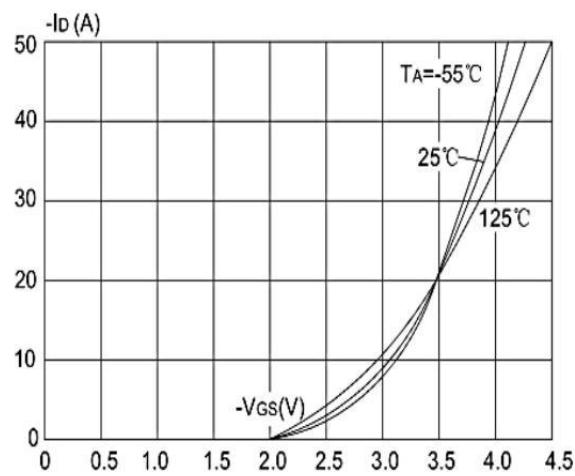


Figure 2: Typical Transfer Characteristics

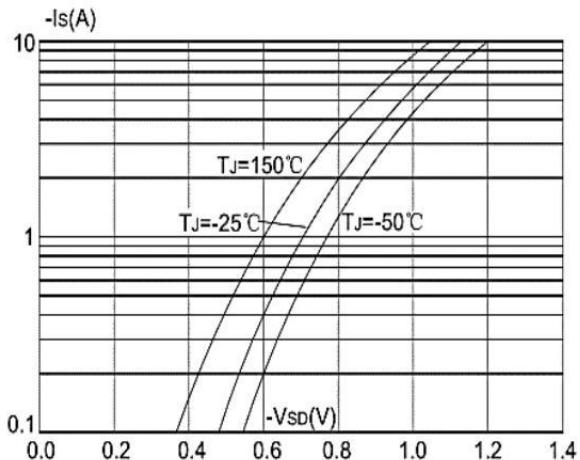


Figure 4: Body Diode Characteristics

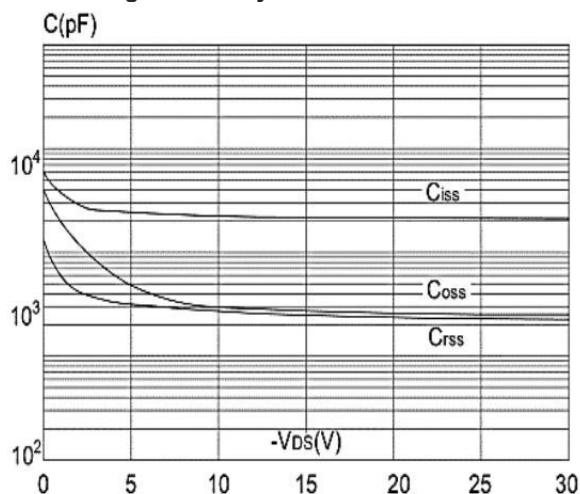


Figure 6: Capacitance Characteristics

## Typical Characteristics

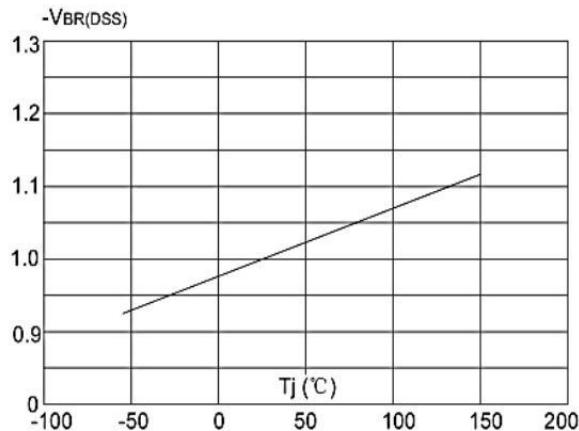


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

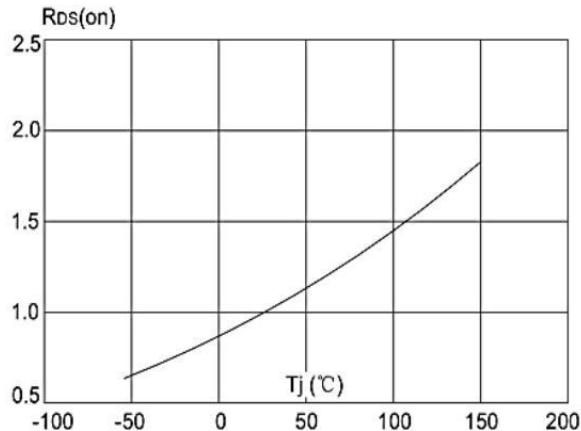


Figure 8: Normalized on Resistance vs. Junction Temperature

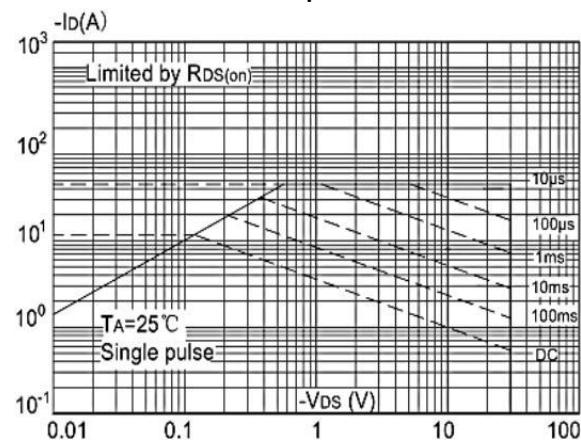


Figure 9: Maximum Safe Operating Area

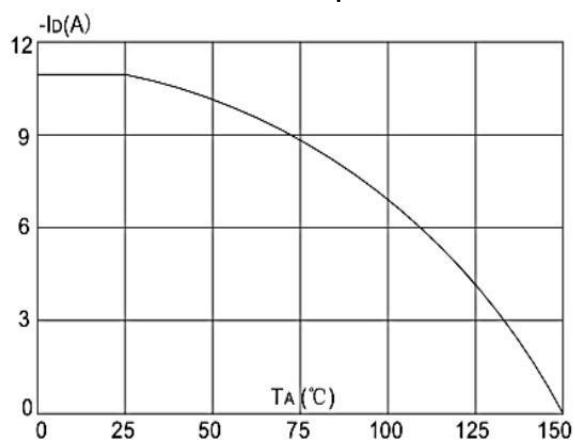


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

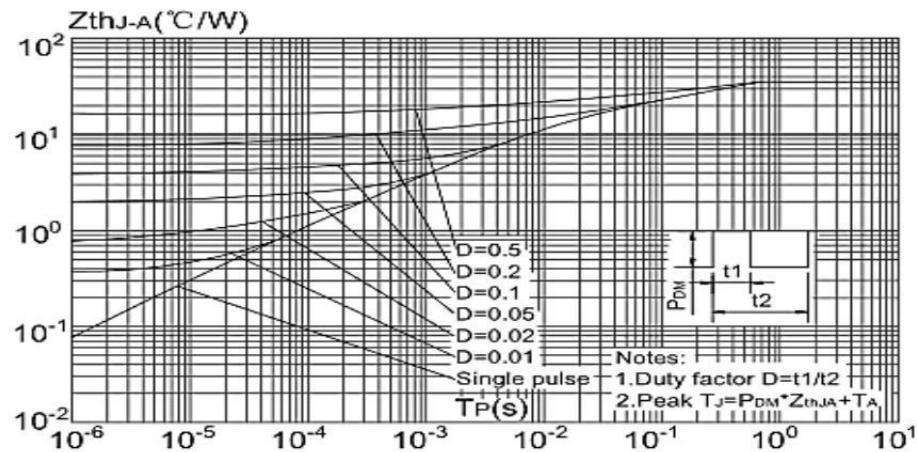
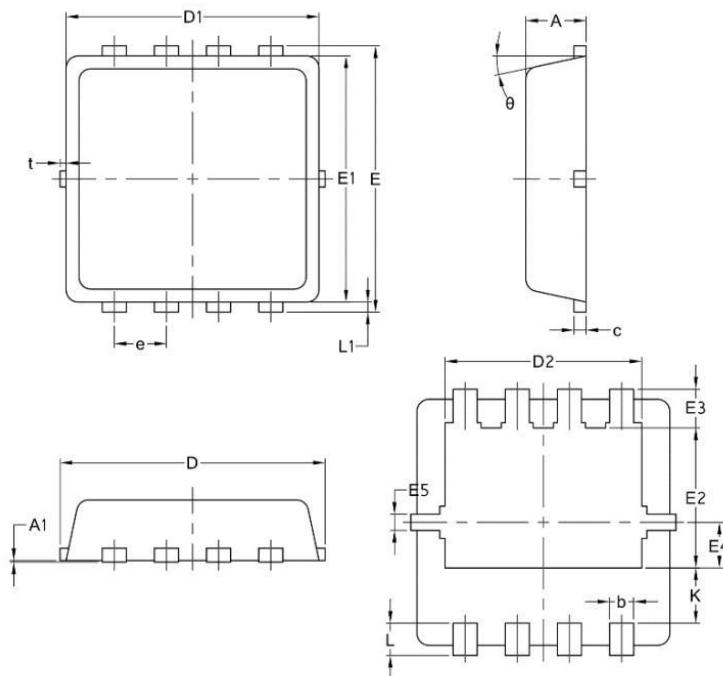


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

## Package Mechanical Data- PDFN3\*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN3*3-8L		5000